

# MEMS 2013

Taipei, Taiwan

## The 26th International Conference on Micro Electro Mechanical Systems

January 20 - 24, 2013

The 26th IEEE International Conference on Micro Electro Mechanical Systems (IEEE MEMS 2013) will be held in Taipei, Taiwan on January 20 – 24, 2013 at the Taipei International Convention Center (TICC). IEEE MEMS is one of the premier annual events reporting research results on every aspect of microsystems technology. This conference reflects the rapid proliferation of the commitment and success of the microsystems research community. Recently, the IEEE MEMS Conference has attracted more than 700 participants, 950+ abstract submissions and has created a forum to present over 300 peer-reviewed, top-quality papers in podium and poster/oral sessions.

**Taiwan – A gem on the Pacific Rim** Well-known for its dynamic economy and technological expertise, Taiwan is home to 23 million inhabitants and to a vibrant high tech sector. With two-thirds of its land covered by forests, what Portuguese explorers originally called **Ilha Formosa** is also home to unique flora and fauna, making this tropical island a birdwatcher's paradise and a spectacular natural wonder.



## CALL FOR ABSTRACTS

### Abstract Classification List

- Fabrication Technologies
- Packaging Technologies
- Materials and Device Characterization
- Mechanical Sensors and Systems
- Physical MEMS
- RF MEMS
- Bio & Chemical Micro Sensors & Systems
- Medical Microsystems
- Micro-Fluidic Components and Systems
- Micro-Actuators
- Energy Harvesting and Power MEMS
- Nano-Electro-Mechanical Devices and Systems

### Important Dates

Abstract Submission Deadline  
- *September 10, 2012*

Notification Due to Authors  
- *October 19, 2012*

Final Papers Due  
- *November 23, 2012*

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[www.mems2013.org](http://www.mems2013.org)

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### Conference Co-chairs

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